



# 600V, 15A, Trench FS II Fast IGBT

### General Description:

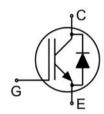
Using MJ's proprietary trench design and advanced FS (Field Stop) second generation technology, the 600V Trench FSII IGBT offers superior conduction and switching performances, and easy parallel operation;

#### Features

- ◆ Trench FSII Technology offering
- ♦ Very low Vce (sat)
- ◆ High speed switching
- ◆ Positive temperature coefficient in V<sub>CE</sub> (sat)
- ◆ Very tight parameter distribution
- ♦ High ruggedness, temperature stable behavior

## Application

- ♦ Air Condition
- Inverters
- ◆ Motor drives







TO-3P

### Package Marking and Ordering Information

		I	
Device	Device Package	Device Marking	
MJ15TD60BP	TO-3P	MJ15TD60BP	

#### Absolute Maximum Ratings (Tc=25°C unless otherwise noted)

Parameter	Symbol	Value	Units
Collector-Emitter Voltage	Vces	600	V
Gate- Emitter Voltage	Vges	±30	V
Collector Current	Ic	30	А
Collector Current @Tc = 100 °C	Ic	15	А
Pulsed Collector Current, tp limited by T <sub>jmax</sub>	Cplus	45	А
turn off safe operating area, VcE=600V, Tj=150°C	_	45	А
Diode Continuous Forward Current @Tc = 100 °C	lF	15	А
Diode Maximum Forward Current	Іғм	45	А
Power Dissipation @ Tc = 25°C	Po	105	W
Power Dissipation @Tc = 100 °C	Po	52.5	W
Operating Junction and Storage Temperature Range	TJ,Tstg	-55 to +175	°C
Maximum Temperature for Soldering	TL	260	°C
Short circuit withstand time V <sub>GE</sub> =15.0V, V <sub>CC</sub> ≤400V, Allowed number of short circuits<1000Time between short circuits:≥1.0s,Tj≤150°C	tsc	5	us





### Thermal Characteristic

Parameter	Symbol	Value	Units
Thermal Resistance, Junction to case for IGBT	Rejc	1.42	°C/W
Thermal Resistance, Junction to case for Diode	Rejc	2.12	°C/W
Thermal Resistance, Junction to Ambient	RөJA	62	°C/W

## Electrical Characteristics (Tc=25°C unless otherwise noted)

Parameter	Symbol	Test Conditions		Value			
Parameter	Syllibol	rest Co	naitions	Min	Тур	Max	Units
Static Characteristics							
Collector-Emitter Breakdown Voltage	V(BR)CES	V <sub>GE</sub> =0V,	Ice=1mA	600	-	-	V
Collector-Emitter Leakage Current	Ices	V <sub>GE</sub> =0V,	/ce=600V	-	-	4	uA
Gate to Emitter Forward Leakage	IGES(F)	V <sub>GE</sub> =+30	V,VcE=0V	-	-	100	nA
Gate to Source Reverse Leakage	IGES(R)	V <sub>GE</sub> =-30	V,VcE=0V	-	-	100	nA
Collector Emitter Seturation Voltage	V	Ic=15A	Tj=25°C	-	1.7	1.9	V
Collector-Emitter Saturation Voltage	VCE(sat)	V <sub>GE</sub> =15V	Tj=100°C	-	1.9	-	V
Gate Threshold Voltage	V <sub>GE(th)</sub>	Ic=1mA	, Vce=Vge	4.0	-	6.0	V
Dynamic Characteristics							
Input Capacitance	Cies	Vce=25V,Vce=0V, f=1MHz		-	1635	-	pF
Output Capacitance	Coss			-	50	-	pF
Reverse Transfer Capacitance	Crss	-		-	30	-	pF
Total Gate Charge	Qg			-	63	-	nC
Gate to Emitter Charge	Qge		V, Ic=15A =15V	-	15	-	nC
Gate to Collector Charge	Qgc	-		-	26	-	nC
Short circuit collector current Max.1000 short circuits Time between short circuits: ≥1.0s	Ic(sc)		Vcc≤400V, Tj≤150°C	-	82	-	А
Switching Characteristics							
Turn-on Delay Time	t <sub>d</sub> (ON)			-	16	-	ns
Rise Time	tr			-	12	-	ns
Turn-Off Delay Time	t <sub>d(OFF)</sub>	-		-	124	-	ns
Fall Time	tr	V <sub>GE</sub> =0/1	0V,Ic=10A 5V, R <sub>g</sub> =5Ω ve Load	-	12	-	ns
Turn-On Switching Loss	Eon	. maucu	vo Loau	-	0.25	-	mJ
Turn-Off Switching Loss	Eoff	-		-	0.12	-	mJ
Total Switching Loss	Ets	-		_	0.37	-	mJ

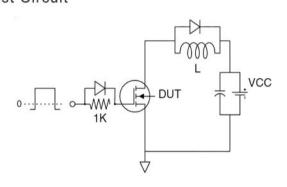




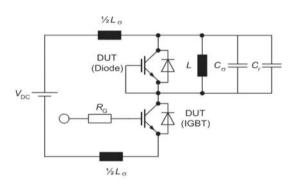
# Electrical Characteristics of the Diode (Tc= 25°C unless otherwise specified):

Doromotor	Symbol	Took Conditions	Rating			l luite
Parameter	Symbol	Test Conditions	Min	Тур	Max	Units
Diode Forward Voltage	VFM	I⊧=15A	-	1.5	1.7	V
Reverse Recovery Time	Trr		-	170	-	ns
Diode Peak Reverse Recovery Current	IRRM	I <sub>F</sub> =15A,di/dt=200A/uS	_	6.5	-	А
Reverse Recovery Charge	Qrr		_	0.7	-	uC
Pulse width ttp≤380μs,δ≤2%	1	1	ı			

## Test Circuit

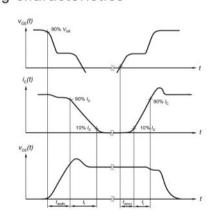


Gate Charge Test Circuit

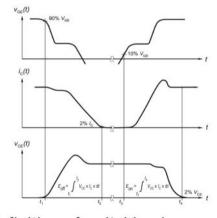


Switch Time Test Circuit

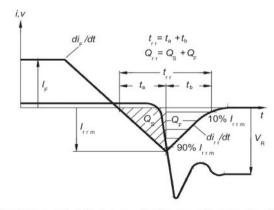
## Switching characteristics



definition of switching times



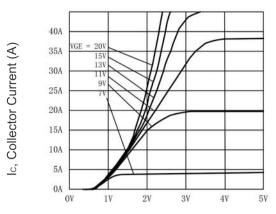
definition of switching losses



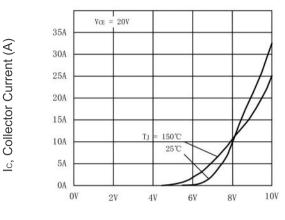
Definition of diode switching characteristics



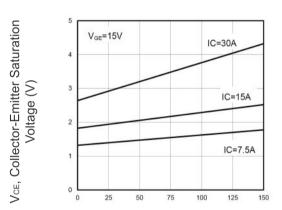
### Typical Electrical and Thermal Characteristics



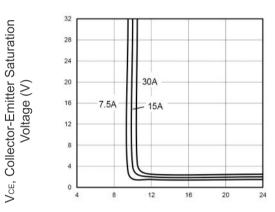
VCE, Collector-Emitter Voltage (V)
Figure 1 Output Characteristics



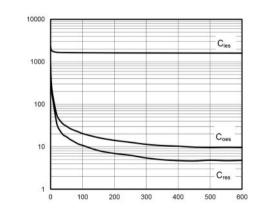
V<sub>GE</sub>, Gate-Emitter Voltage (V)
Figure 2 Transfer Characteristics



TJ, Junction Temperature (°C)
Figure 3 V<sub>CEsat</sub> vs. Case Temperature

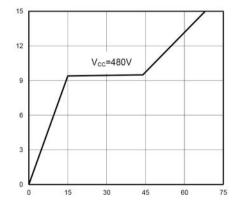


VGE, Gate-Emitter Voltage (V)
Figure 4 Saturation Voltage vs. VGE



Capacitance (pF)

Vce, Collector-Emitter Voltage (V)
Figure 5 Capacitance Characteristics



Qg, Total Gate Charge (nC)
Figure 6 Gate charge waveform

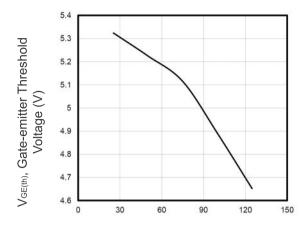
VGE, Gate-Emitter Voltage (V)

Ptot, Power Dissipation (W)

Ic, Current Rating (A)

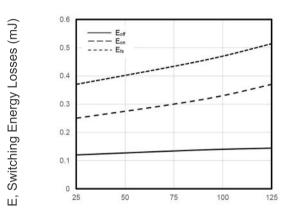


### Typical Electrical and Thermal Characteristics



TJ, Junction Temperature (°C)

Figure 7 Gate-emitter Threshold Voltage as a Function of Junction Temperature



TJ, Junction Temperature (°C)

Figure 9 Typical Switching Times as a Function of Junction Temperature

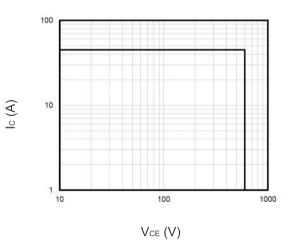
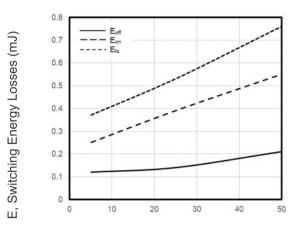
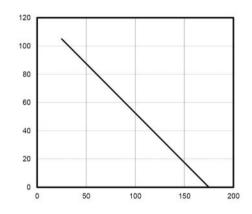


Figure 11 Reverse Bias SOA



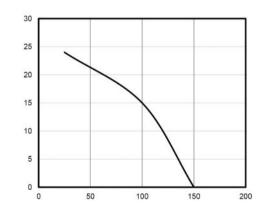
R<sub>G</sub>, Gate Resistor (Ω)

Figure 8 Typical Switching Times as a Function of Gate Resistor



Tc, Case Temperature (°C)

Figure 10 Power Dissipation as a Function of Case Temperature



Tc, Case Temperature (°C)

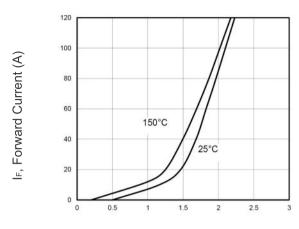
Figure 12 Current De-rating



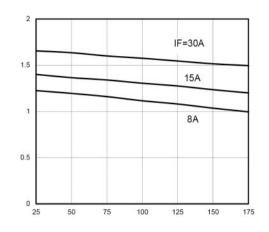


V<sub>F</sub>, Forward Voltage (V)

## Typical Electrical and Thermal Characteristics (continued)



V<sub>F</sub>, Forward Voltage (V)
Figure 13 Forward Characteristics

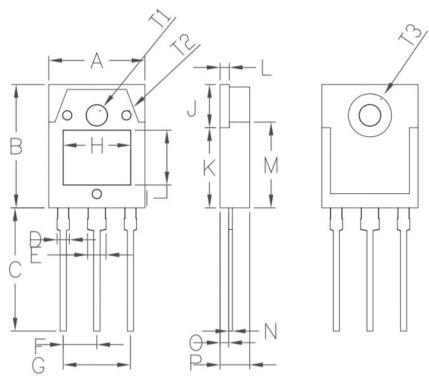


TJ, Junction Temperature (°C)
Figure 14 VF vs. temperature





# TO-3P-3L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
Α	15.50	15.70	0.61	0.62	
В	19.70	20.10	0.78	0.79	
С	20.10	20.50	0.79	0.81	
D	2.	00	0.	08	
E	3.	00	0.	12	
F	5.	45	0.	21	
G	10	.90	0.	43	
Н	10.80	11.00	0.43	0.43	
I	8.80	9.00	0.35	0.35	
J	6.85	7.15	0.27	0.28	
К	12.75	13.05	0.50	0.51	
L	1.49	1.51	0.06	0.06	
М	13.70	14.00	0.54	0.55	
N	0.59	0.61	0.02	0.02	
0	1.32	1.48	0.05	0.06	
Р	4.70	4.90	0.19	0.19	
S	4	4° 0.16°			
T1	3.50		0.14		
T2	1.50		0.06		
Т3	7.	0.	28		





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